

WHAT IS CLAIMED IS:

1. A module, comprising:

3 a hermetically-sealable shell having first and second terminal
sets;

4 a first surface acoustic wave (SAW) circuit, located within
5 said shell and couplable to said first terminal set, that filters
6 signals in a first band of communications frequencies; and

7 a second SAW circuit, located within said shell and couplable
8 to said second terminal set, that filters signals in a second band
9 of communications frequencies.

2. The module as recited in Claim 1 wherein said first band
2 of communications frequencies comprises a frequency between 800 and
3 900 megahertz.

3. The module as recited in Claim 1 wherein said second band
2 of communications frequencies comprises a frequency between 1800
3 and 1900 megahertz.

4. The module as recited in Claim 1 wherein said shell
2 comprises a common base that supports said first and second SAW
3 circuits.

5. The module as recited in Claim 1 further comprising a lid
2 coupled to said shell to form a hermetic enclosure that surrounds
3 said first and second SAW circuits.

6. The module as recited in Claim 1 wherein said first and
2 second SAW circuits are located on a common piezoelectric
3 substrate.

7. The module as recited in Claim 6 further comprising a
2 crosstalk shield located between said first and second SAW
3 circuits.

11/8/74
Class 29/25.35
Mar 2/20/82

8. A method of manufacturing a circuit module, comprising:
providing a hermetically-sealable shell having first and
second terminal sets;

placing a first surface acoustic wave (SAW) circuit in said
shell, said first SAW circuit capable of filtering signals in a
first band of communications frequencies;

coupling said first SAW circuit to said first terminal set;

placing a second SAW circuit in said shell, said second SAW
circuit capable of filtering signals in a second band of
communications frequencies;

coupling said second SAW circuit to said second terminal set;

and

placing a lid on said shell to form an enclosure that
surrounds said first and second SAW circuits.

9. The method as recited in Claim 8 wherein said first band
of communications frequencies comprises a frequency between 800 and
900 megahertz.

10. The method as recited in Claim 8 wherein said second band
of communications frequencies comprises a frequency between 1800
and 1900 megahertz.

11. The method as recited in Claim 8 wherein said shell
2 comprises a common base that supports said first and second SAW
3 circuits.

12. The method as recited in Claim 8 wherein said enclosure
2 is hermetic.

13. The method as recited in Claim 8 wherein said first and
2 second SAW circuits are located on a common piezoelectric
3 substrate.

14. The method as recited in Claim 13 further comprising
2 forming a crosstalk shield between said first and second SAW
3 circuits.

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15. A module, comprising:

a hermetically-sealable shell having first and second terminal
3 sets;

4 a first surface acoustic wave (SAW) circuit, located within
5 said shell and couplable to said first terminal set, that filters
6 signals in a first band of communications frequencies;

7 a second SAW circuit, located within said shell and couplable
8 to said second terminal set, that filters signals in a second band
9 of communications frequencies; and

10 a lid coupled to said shell and forming an enclosure that
11 surrounds said first and second SAW circuits.

12 16. The module as recited in Claim 15 wherein said first band
13 of communications frequencies comprises a frequency between 800 and
14 900 megahertz.

15 17. The module as recited in Claim 15 wherein said second
16 band of communications frequencies comprises a frequency between
17 1800 and 1900 megahertz.

18 18. The module as recited in Claim 15 wherein said shell
19 comprises a common base that supports said first and second SAW
20 circuits.

19. The module as recited in Claim 15 wherein said enclosure
2 is hermetic.

20. The module as recited in Claim 15 wherein said first and
2 second SAW circuits are located on a common piezoelectric
3 substrate.

21. The module as recited in Claim 20 wherein a crosstalk
2 shield is located between said first and second SAW circuits.